



European Thermodynamics Limited

Intelligent Thermal Management

TE Modules Production and Control: Present and Future

Kevin Simpson

European Thermodynamics Ltd: an introduction

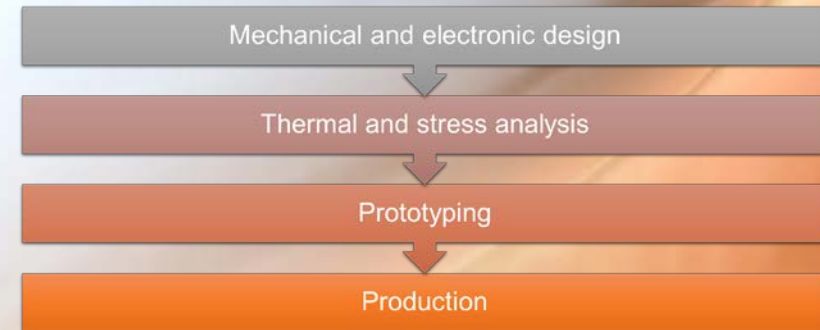
- Founded in 2001. Private Ltd Co.
- Bespoke thermal management
- 26 full and part-time staff
- R&D department (6 Researchers) & Engineering (8 Engineers and 2 Technicians)
- €5m annual turnover
- R&D projects part-funded by:



Technology Strategy Board
Driving Innovation



BESPOKE DEVELOPMENT FOR THERMAL MANAGEMENT



LEADING SECTORS



Telecomm



TV & Broadcast



Lab & Medical



Automotive

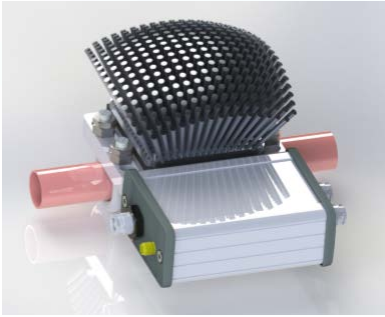


Industrial

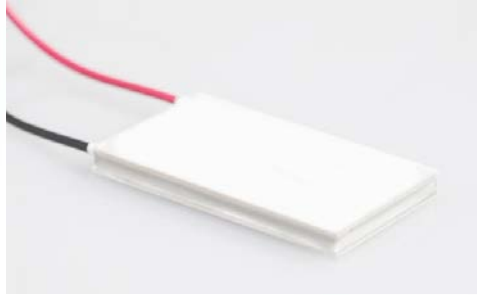


Military

New products

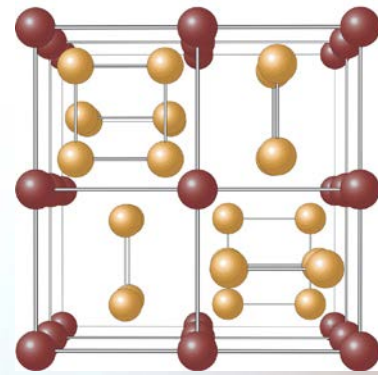


Wireless energy harvesting kit

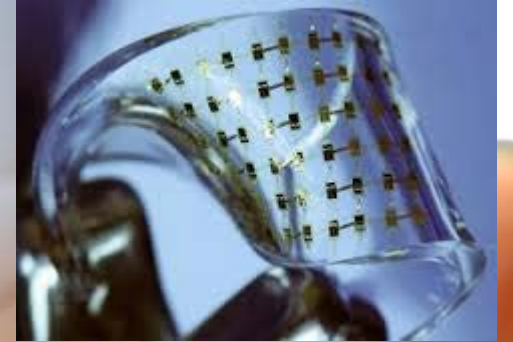


New thermoelectric cooler modules

R&D



Novel thermoelectric materials



Flexible TEGs



Temperature controller



Thermoelectric assembly

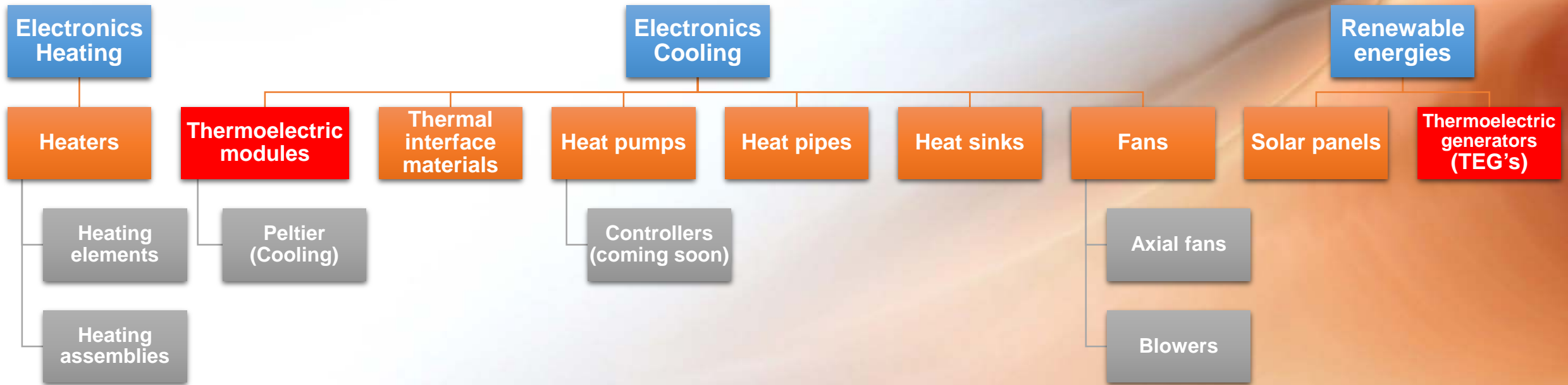


PCB/TEG fabrication



TEG reliability analysis

Products



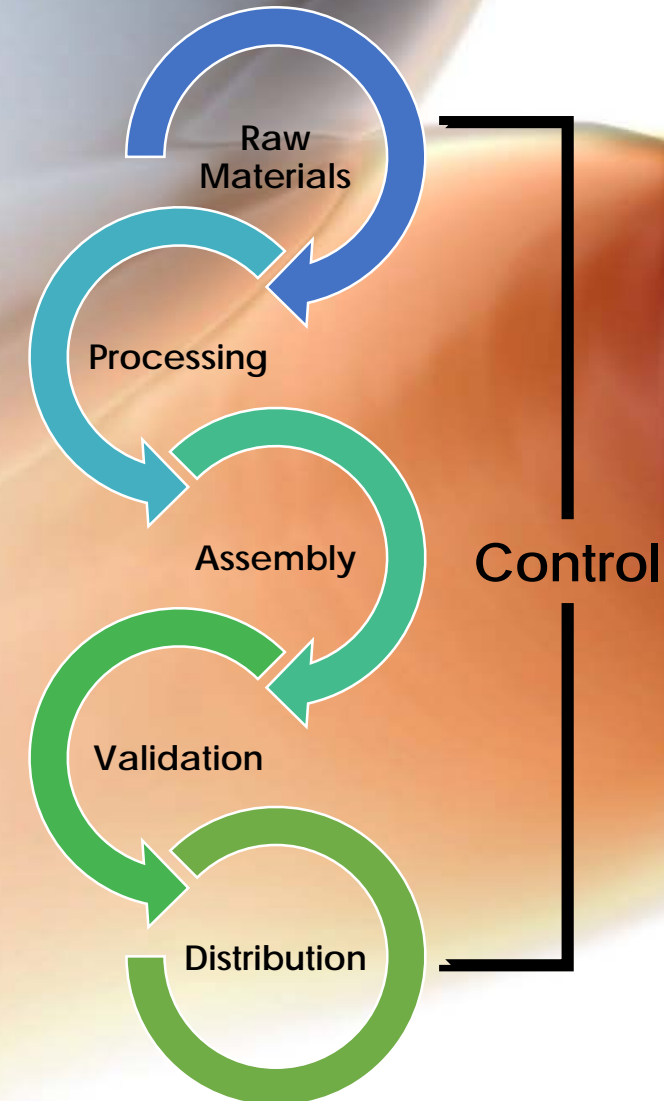
Current Research into Manufacturing

✚ Aims:

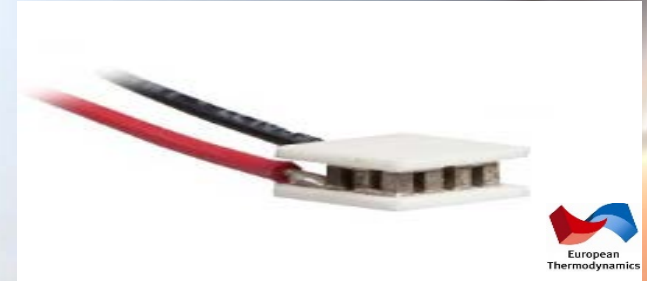
- ✚ Establish a UK supply chain for Thermoelectric module manufacture
- ✚ Bespoke and unique module design and fabrication
- ✚ Increase material efficiency and production autonomy
- ✚ Novel thermoelectric materials to exploit alternative markets through USPs
 - ✚ Powder formulation, Sintering Process, Metallisation, Cutting, Joining and module assembly
- ✚ Design and manufacture high reliability devices

✚ Projects:

- ✚ PrinTEG-Automated production line for TEGs
- ✚ ElectroTEG-Electrodeposition of TE material to increase efficiency of manufacture
- ✚ Prestege-Screen printing of thermoelectric pastes. Flexible substrates
- ✚ Enhanced-Ink jet printing of TE inks. Complex module designs on flexible substrates



Control Stages



Material Consolidation

Thermoelectric Pellets Machining

Thermoelectric Device Assembling

Control Methods

- Seebeck
- Thermal Conductivity
- Electrical Resistivity
- Mechanical Testing

- Dimensional Control
- Contact Resistance
- Metallisation Barriers

- Harman Method
- AC Resistance
- Module Performance Test Rig

Prestige & Enhanced Screen/Ink-Jet Printed TEGs

Silk Screen Printing



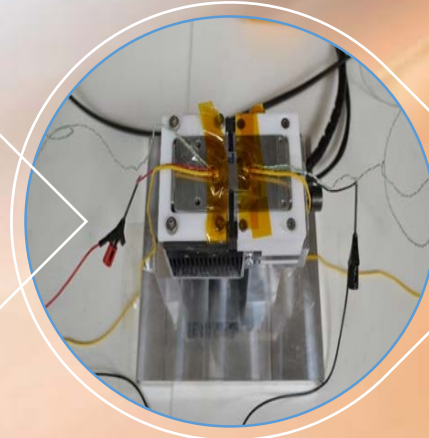
- Utilising established manufacturing techniques applied into reproducible/scalable TEG manufacture
- Reduced material wastage
- Validation of controlled characteristics:
 - Bespoke Seebeck test rig
 - 4 point probe sheet electrical resistivity



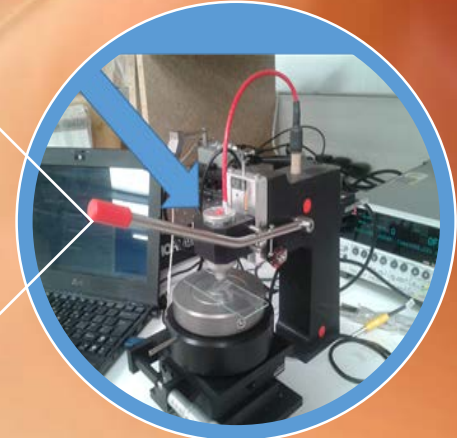
Ink-Jet Printing



Firing/Sintering



Seebeck Characterisation



Electrical Characterisation

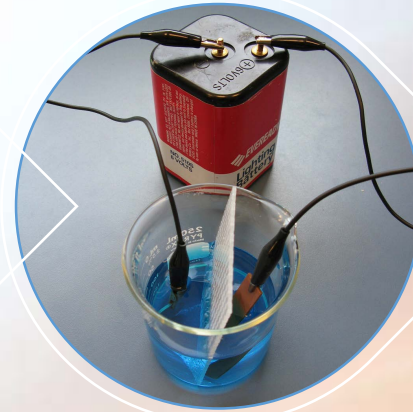
ElectroTEG

Electrodeposited TEGs

- Developing novel plating formulation
- Low cost and scalable process
- Reduced material wastage
- Full prototype module characterisation:
 - AC resistance
 - Power performance
 - Harman measurements
 - Hall measurements



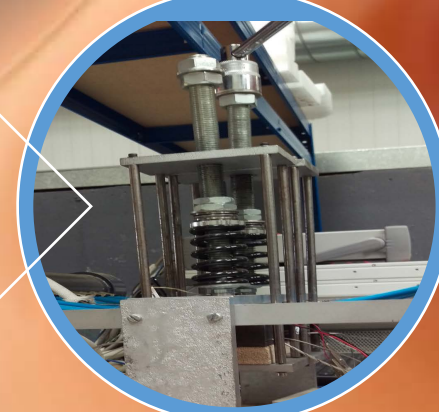
Solution
Formulation



TE
Electroplating



Material
joining



Performance
Characterisation

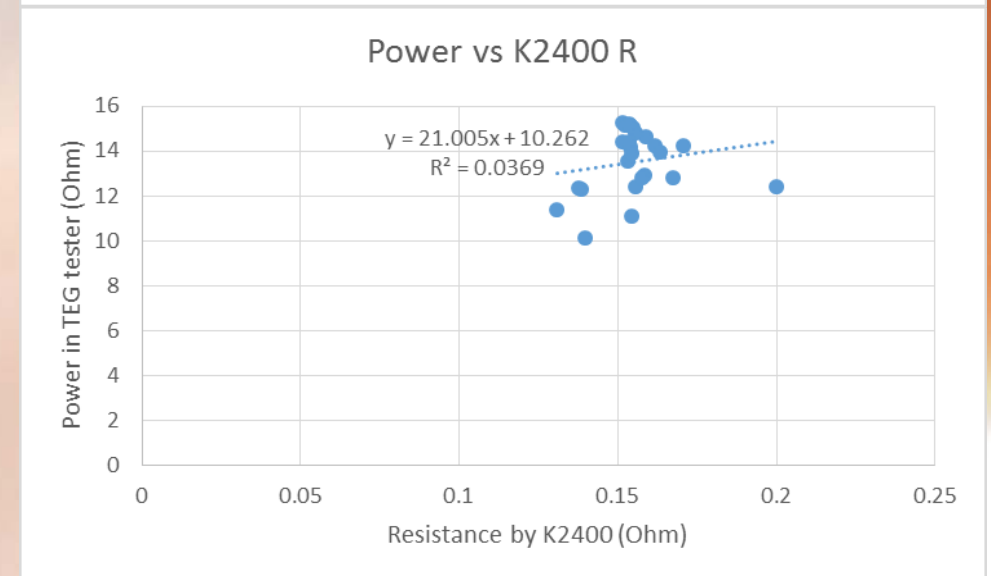
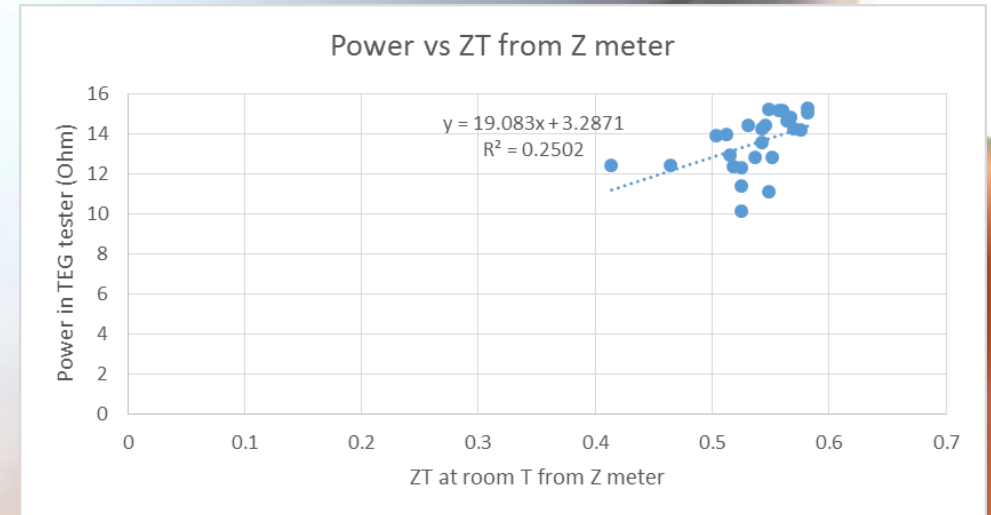
PrinTEG: Control Within Fabrication Process

- ✚ Accuracy and reliability:
 - ✚ Placement accuracy to approximately $\pm 20\mu\text{m}$.
 - ✚ Minimum spacing $100\mu\text{m}$.
 - ✚ Higher: Voltage, fill-factor/power density.
 - ✚ 200 pellets placed accurately.
 - ✚ Minimal human interaction.
 - ✚ Continuous production process.
 - ✚ Approximately 4 minutes to accurately position pellets for a module.
- ✚ Validation:
 - ✚ Pickup inspection-Single pellets.
 - ✚ Cyberoptics, optical inspection-macroscopic inspection.

**Equipment running at 30% speed for purpose of video.*

PrinTEG: Control Within Fabrication Process

- For industrial production levels, inline characterisation techniques must be developed for quality control
- Necessary requirements:
 - Quick measurement
 - Non-destructive
 - Accurate
 - Able to extrapolate from measurement
- Current issues arise with correlation between different measurement techniques e.g.:
 - TEG matched power point value (slow/offline)
 - Z-meter/Harman measurement (quick/inline)
 - 4-point probe resistance (quick/inline)
 - AC Resistance (quick/inline)



Device Performance

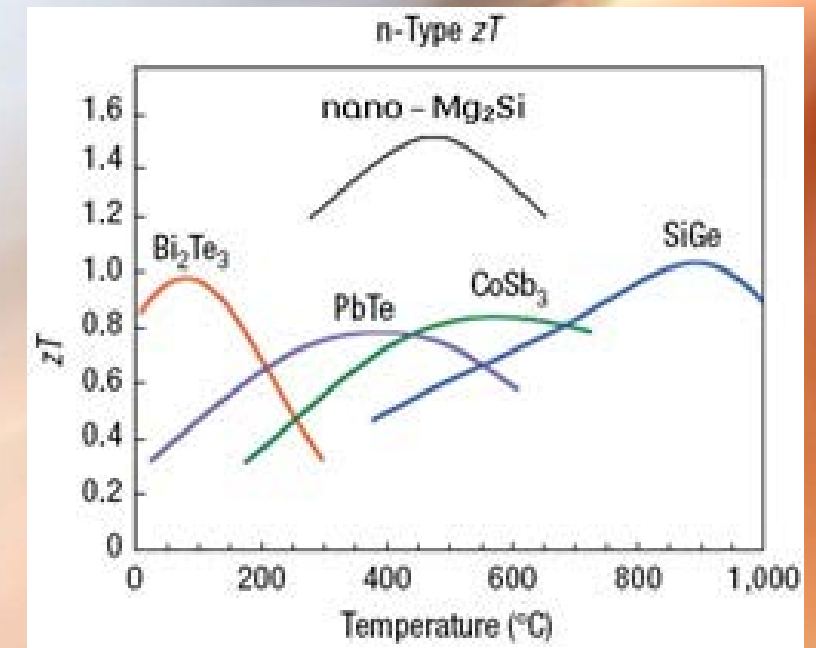
- ✚ ETL has carried out a literature review on module characterisation techniques used by manufacturing companies worldwide
 - ✚ There is no standard method for accelerated lifetime tests
 - ✚ The variation in test methods lead to non comparable data
 - ✚ Many follow a variety of military standards designed for general electrical systems
 - ✚ The difficulty in unifying lifecycle testing is that there are a multitude of applications that thermoelectric modules are used for
 - ✚ We propose defining a set of lifecycle testing methods which are compatible for a variety of general applications
 - ✚ This will benefit end users and material developers
- ✚ Non-unified test categories:
 - ✚ Mechanical shock
 - ✚ Vibration
 - ✚ Shear force
 - ✚ High temperature soak
 - ✚ Thermal cycling
 - ✚ Thermal shock
 - ✚ Temperature gradient

Thermal cycling test rig developed to assess reliability →



Desirable Material Characteristics

- Characteristics for determining suitability of new materials to realise material-prototype and prototype-mass production transition:
 - Material abundance and low toxicity
 - Estimated cost of processing and manufacturing route
 - Average ZT or peak ZT
 - Thermal stability > Ease of joining
 - Ease of metallisation
 - Mechanical characteristics (as a structural component)
 - Tailoring properties based on proposed use
 - E.g. Balancing power factor with thermal conductivity based on heat source and sink properties



Problems to Overcome

- ✚ Directions for determining performance of new materials
 - ✚ Estimated cost of processing and manufacturing route
 - ✚ Average ZT or peak ZT
 - ✚ Consider feedback from **module** lifetime cycling
- ✚ Inline characterisation issues: Devising a method which can take a quick measurement that accurately represents quality of a device
- ✚ Standardising methods for characterisation throughout supply chain and manufacturing
 - ✚ Promote accurate comparisons for a range of general systems/applications
 - ✚ Continuity/traceability
- ✚ **End user confidence in UK supplied thermoelectric modules**

Challenges

- ✚ Oxidation
- ✚ Metallisation
- ✚ BiTe replacement
- ✚ Mechanical strength
- ✚ Brazing formulations
- ✚ N and P type performance matching
- ✚ Thermal stress problem
- ✚ Low cost process development
- ✚ Module reliability/material stability
- ✚ Interfacing (materials or direct application)